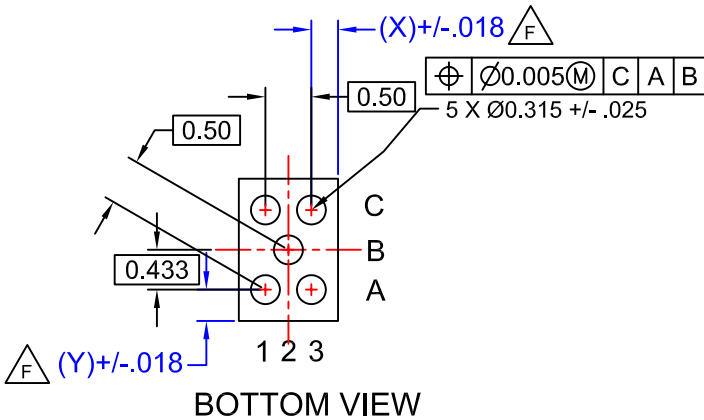
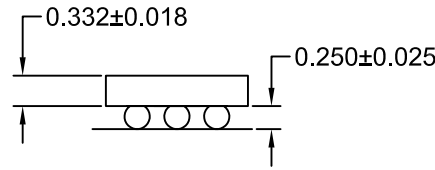
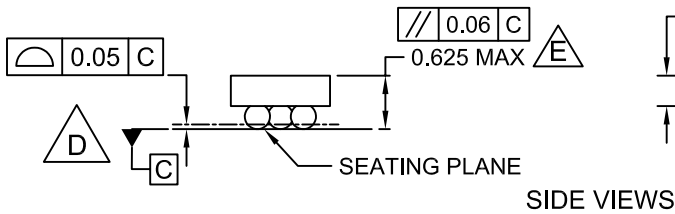
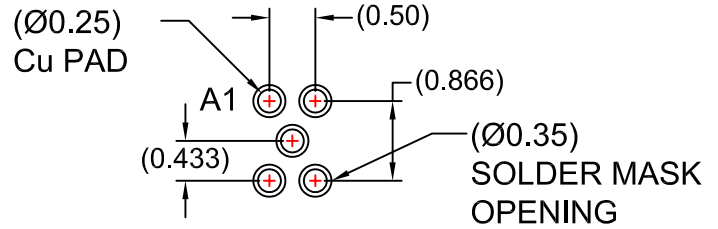
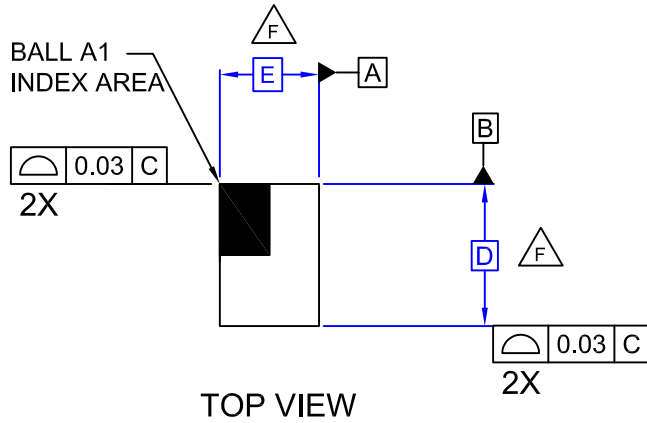


REVISIONS

REV	DESCRIPTION	DATE	BY/SITE
1	INITIAL DRAWING RELEASE	27-7-2006	H.ALLEN/FSME
2	Removed Laminate and increased silicon thickness	19-4-2007	H.ALLEN/FSME
3	Removed line showing lamination layer on rev 1	05-05-2007	SMARTIN/FSME
4	CHANGE TO REV2 BALL TOLERANCE AND NOTE FOR CONSISTENCY	05-05-2007	SMARTIN/FSME
5	REVERTED TO REVISION 3,UPDATED DWG NAME	19-02-2008	H.ALLEN/FSME



NOTES:

- A. NO JEDEC REGISTRATION APPLIES
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 582 MICRONS +/- 43 MICRONS (539-625 MICRONS)
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. BALL COMPOSITION: Sn95.5Ag3.9Cu0.6 SAC405 ALLOY
- H. DRAWING FILENAME: MKT-UC005AArev5

FSC INTERNAL NOTE: TYPE 1 WL CSP IS PROVIDED BY AMKOR ONLY!

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN H.ALLEN	19-02-08	5BALL, TYPE 1 WL-CSP, 0.5MM PITCH, 2X2 ARRAY WITH CENTER BALL			
DFTG. CHK. L.ENGLAND	19-02-08				
ENGR. CHK.					
		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-UC005AA	REV 5
		DO NOT SCALE DRAWING		SHEET 1 of 1	